



Product Change Notification

107775 - 03

Information in this document is provided in connection with Intel products. No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document. Except as provided in Intel's Terms and Conditions of Sale for such products, Intel assumes no liability whatsoever, and Intel disclaims any express or implied warranty, relating to sale and/or use of Intel products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright or other intellectual property right. Intel products are not intended for use in medical, life saving, or life sustaining applications. Intel may make changes to specifications and product descriptions at any time, without notice.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com

Copyright © Intel Corporation 2009. Other names and brands may be claimed as the property of others.

Celeron, Centrino, Intel, the Intel logo, Intel Core, Intel NetBurst, Intel NetMerge, Intel NetStructure, Intel SingleDriver, Intel SpeedStep, Intel StrataFlash, Intel Viiv, Intel XScale, Itanium, MMX, Paragon, PDCharm, Pentium, and Xeon are trademarks or registered trademarks of Intel Corporation or its subsidiaries in the United States and other countries.

Learn how to use Intel Trade Marks and Brands correctly at <http://www.intel.com/intel/legal/tmusage2.htm>.



Product Change Notification

Change Notification #: 107775 - 03
Change Title: Intel(R) IP Network Server NSC2U SAS Front Panel Board, PCN 107775-03, Product Design, Larger grounding pad increases EMI margin, Reason for Revision: Update TA revision numbers
Date of Publication: January 12, 2009

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Nov 21, 2008
---	--------------

Description of Change to the Customer:

Reason for Revision: Update TA revision numbers

Increased the size of the copper grounding/mounting pad on the SFP (SAS Front Panel) board to increase the EMI (ElectroMagnetic Interference) margin. This change increases the selection of VRMs (Voltage Regulator Modules) used on the board.

Customer Impact of Change and Recommended Action:

Intel has fully validated the change and expects the customer validation requirement to be minimal to none.

Products Affected / Intel Ordering Codes:

Pre Change Product Code	Pre Change MM#	Pre Change TA	Post Change Product Code	Post Change MM#	Post Change TA
NSCD0201W	889357	NA	NSCD0202W	900074	E49436-001
NSCA0201W	889358	NA	NSCA0202W	900075	E49435-001
NSCFPIOBDLPW	889812	D89056-006	NA	NA	D89056-007

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
August 27, 2007	00	Originally Published PCN
May 16, 2008	01	Publish revised cut-in date
June 27, 2008	02	Revise TA numbers
January 12, 2009	03	Update TA revision numbers